

**CHECK LIST FOR SUBSCRIPTION**

INSTITUTION

Name

Mail adress

Address of shipment

Tel number for shipment

Dicing  NO OR  YES: DICING MAP

TABLE OF LAYER

Layer	Acronym	Description	Light field or Dark field	Minimum CD en nm	CD 1	CD2	CD3	CD range * target dose	Control alignment with layer	maximum OVL acceptable	Sweep dose
for example 1	FC	Fiber coupler	D	S 315	S315	L315	S315/L315	No	none		(No)
2	WG	Waveguide	L	L 120	L120-L 170	variable	variable	120-170	2 on 1	+/-150nm	(yes)

S: space L: line D:diameter  
 CD range\* : Maximum( max - min )= 100 nm

USER TABLE OF LAYER

Layer	Acronym	Description	Light field or Dark field	Minimum CD	CD 1	CD2	CD3	CD range * target dose	Control alignment with layer	maximum OVL acceptable	Sweep dose
1	FC	Fiber coupler	D					No	none	No	(No)
2	WG	Waveguide	L						2 on 1		(yes)

Specify the number of wafers and their specifications upon possible process variations in a table

for example:

Step	Processing steps / Wafer	wafer 1	wafer 2	wafer 3	wafer 4
1	Litho of grating				
2	CD of grating				
3	Partial etching of grating 70nm				
4	Stripping				
5	Oxide deposition for hard mask				
6	Litho of waveguide				
7	CD litho of Waveguide (CD1;CD2;CD3)				
8	Etch of hard mask				
9	Stripping				
10	Etch of 220nm silicon down to the BOX				
11	CD etching of Waveguide (CD1;CD2;CD3)				
12	Thermal oxidation 10nm				
13	Observation, analysis of fab, report				
14	Cladding Resist				
15	Cladding HDP SiO2 700nm				
16	Dicing	dicing map	dicing map		